

Abstract of the Invention

A thick wafer is diced by partially dicing a first side to form a first dice, flipping the wafer so that the first side is now in contact with a dicing tape, and dicing a second side. The dicing of the second side may be achieved by aligning a dicing tool to the first dice and/or alignment marks on the wafer. The thick wafer may be a composite wafer including two or more wafers bonded together. These two wafers may be different thicknesses and/or different materials.

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